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Contents

ix xiii	Authors Conference Committee
	KEYNOTE SESSION
9426 02	Optical lithography with and without NGL for single-digit nanometer nodes (Keynote Paper) [9426-1]
	PUSHING OPTICAL LIMIT
9426 04	Evolving optical lithography without EUV (Invited Paper) [9426-3]
9426 05	Mask 3D induced phase and the mitigation by absorber optimization (Invited Paper) [9426-4]
9426 06	Patterning process exploration of metal 1 layer in 7nm node with 3D patterning flow simulations [9426-5]
	IMAGE AND PROCESS CONTROL
9426 07	Impact of bandwidth on contrast sensitive structures for low k1 lithography [9426-6]
9426 08	Solution for high-order distortion on extreme illumination condition using computational prediction method $[9426\mathchar`-7]$
9426 09	Optimum ArFi light source bandwidth for 10nm node logic imaging performance [9426-8]
9426 OB	Single lithography exposure edge placement model [9426-10]
	NON-IC APPLICATIONS
9426 0C	Multicolor, visible-light nanolithography (Invited Paper) [9426-11]
9426 OD	Progresses in 300mm DUV photolithography for the development of advanced silicon photonic devices (Invited Paper) [9426-12]
9426 OE	Double-sided diffractive photo-mask for sub-500nm resolution proximity i-line mask-aligner lithography [9426-13]
9426 OF	Optimization methods for 3D lithography process utilizing DMD-based maskless grayscale photolithography system [9426-14]

	MASK TOPOGRAPHY: JOINT SESSION WITH CONFERENCES 9422 AND 9426
9426 OH	Mask-induced best-focus-shifts in DUV and EUV lithography [9426-16]
9426 01	Intensity and phase fields behind phase shifting masks studied with high resolution interference microscopy [9426-17]
	MULTIPLE PATTERNING AND SMO
9426 OJ	Study of cut mask lithography options for sub-20nm metal routing [9426-18]
9426 OK	Inverse lithography using sparse mask representations [9426-19]
9426 OL	RET selection on state-of-the-art NAND flash [9426-20]
9426 0M	Pixel-based ant colony algorithm for source mask optimization [9426-21]
9426 ON	Low-contrast photoresist development model for OPC applications at 10nm node [9426-22]
	MASK AND WAFER TOPOGRAPHY MODELING
9426 00	Characterizing the dependence of thick-mask edge effects on illumination angle using AIMS images (CYMER Best Student Paper Award in Microlithography) [9426-23]
9426 OP	Accurate, full chip 3D electromagnetic field model for non-Manhattan mask corners [9426-24]
9426 0Q	A pattern- and optics-independent compact model of Mask3D under off-axis illumination with significant efficiency and accuracy improvements [9426-25]
9426 OR	Printing circuits with 4nm feature size: similarities and differences between EUV and optical lithographies [9426-26]
9426 OS	Rigorous wafer topography simulation for investigating wafer alignment quality and robustness $\left[9426\text{-}27\right]$
	OPC AND MODELING
9426 OT	Investigating deprotection-induced shrinkage and retro-grade sidewalls in NTD resists [9426-29]
9426 OU	Alternative to ILT method for high-quality full-chip SRAF insertion [9426-30]
9426 0V	Uncertainty aware site selection method for OPC model calibration [9426-31]
9426 OW	Experiments using automated sample plan selection for OPC modeling [9426-32]

9426 OX	Optical proximity correction with hierarchical Bayes model [9426-33]
9426 OY	Application of SEM-based contours for OPC model weighting and sample plan reduction $\left[9426\text{-}34\right]$
	DFM (DESIGN AND LITHO OPTIMIZATION): JOINT SESSION WITH CONFERENCES 9426 AND 9427
9426 10	Hot spots prediction after etching process based on defect rate [9426-36]
9426 11	Hybrid OPC flow with pattern search and replacement [9426-37]
	OVERLAY OPTIMIZATION: JOINT SESSION WITH CONFERENCES 9424 AND 9426
9426 12	Overlay improvement methods with diffraction based overlay and integrated metrology [9426-38]
9426 13	Intra-field overlay correction for illumination based distortion [9426-39]
9426 14	Wafer to wafer overlay control algorithm implementation based on statistics [9426-40]
	TOOLINGS
9426 16	Immersion and dry scanner extensions for sub-10nm production nodes [9426-46]
9426 17	Latest performance of ArF immersion scanner NSR-S630D for high-volume manufacturing for 7nm node $[9426\text{-}42]$
9426 18	New ArF immersion light source introduces technologies for high-volume 14nm manufacturing and beyond [9426-43]
9426 19	Total lithography system based on a new application software platform enabling smart scanner management $\left[9426\text{-}44\right]$
9426 1A	Green solution: 120W ArF immersion light source supporting the next-generation multiple-pattering lithography [9426-45]
	POSTERS: IMAGE AND PROCESS CONTROL
9426 1C	Comparing the experimental resist pattern width with aerial image intensity in high-NA projection lens [9426-48]
9426 1D	Advanced process characterization using light source performance modulation and monitoring [9426-49]
9426 1E	Analytical analysis for impact of polarization aberration of projection lens on lithographic imaging quality [9426-80]

	POSTERS: MASK AND WAFER TOPOGRAPHY
9426 1F	Reducing the substrate dependent scanner leveling effect in low-k1 contact printing [9426-50]
9426 1G	A fast and flexible library-based thick-mask near-field calculation method [9426-51]
9426 1H	Focus shift impacted by mask 3D and comparison between Att. PSM and OMOG [9426-52]
	POSTERS: MULTIPLE PATTERNING AND SMO
9426 1J	120W ArF laser with high-wavelength stability and efficiency for the next-generation multiple-patterning immersion lithography [9426-54]
9426 1K	Forbidden pitches: causes, source optimization, and their role in design rules [9426-55]
9426 1L	Source optimization using particle swarm optimization algorithm in photolithography [9426-79]
	POSTERS: NON-IC APPLICATIONS
9426 1M	Advanced Mask Aligner Lithography (AMALITH) [9426-56]
	POSTERS: OPC MODEL
042/ 10	An improved with all the smaller medal to simulate metals 2D and resist affects [0427, 50]
9426 10	An improved virtual aberration model to simulate mask 3D and resist effects [9426-58]
9426 1P	Evaluation of compact models for negative-tone development layers at 20/14nm nodes [9426-59]
9426 1Q	Photoresist 3D profile related etch process simulation and its application to full chip etch compact modeling [9426-60]
9426 1R	Resist profile modeling with compact resist model [9426-61]
9426 1S	Impacts of post OPC shapes on pattern [9426-62]
9426 1T	Calibrating etch model with SEM contours [9426-78]
	POSTERS: OPTICAL PROXIMITY CORRECTION
0427.411	
9426 1U	7nm logic optical lithography with OPC-Lite [9426-63]
9426 1V	OPC solution by implementing fast converging methodology [9426-64]

9426 1W	The comparison of various strategies of setting up an OPC repair flow with respect to process window constraints [9426-65]
9426 1X	Model-based Hot Spot Fixing (HSF) by using target point control function [9426-66]
9426 1Y	Sub-Resolution Assist Feature (SRAF) printing prediction using logistic regression [9426-67]
9426 1Z	Accurate and fast computation of transmission cross coefficients [9426-68]
9426 21	The study of lithography conditions to use advanced resist performance properly [9426-70]
	POSTERS: TOOLINGS
9426 23	Modeling and simulation of the beam steering unit [9426-72]
9426 24	DUV ArF light source automated gas optimization for enhanced repeatability and availability [9426-73]
9426 25	Performance of ETC controller in high-volume production [9426-74]
9426 26	Enabling CoO improvement thru green initiatives [9426-75]
9426 27	New robust and highly customizable light source management system [9426-76]
9426 28	Extending green technology innovations to enable greener fabs [9426-77]